



PMEG4010CEGW

40 V, 1 A low VF MEGA Schottky barrier rectifier

23 November 2016

Product data sheet

1. General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier diode rectifier with an integrated guard ring for stress protection, encapsulated in an SOD123 small Surface-Mounted Device (SMD) plastic package.

2. Features and benefits

- Forward current: $I_F \leq 1$ A
- Reverse voltage: $V_R \leq 40$ V
- Low forward voltage typ. $V_F = 490$ mV
- Low reverse current typ. $I_R = 6$ μ A
- Small SMD plastic package
- AEC-Q101 qualified

3. Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Automotive applications

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_F	forward current	$T_{sp} \leq 55$ °C		-	-	1	A
V_R	reverse voltage	$T_j = 25$ °C		-	-	40	V
V_F	forward voltage	$I_F = 1$ A; $t_p \leq 300$ μ s; $\delta \leq 0.02$; $T_j = 25$ °C		-	490	570	mV
I_R	reverse current	$V_R = 40$ V; pulsed; $T_j = 25$ °C	[1]	-	6	50	μ A

[1] Very short test pulse to prevent junction self-heating.



5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode ^[1]	 SOD123	 sym001
2	A	anode		

[1] The marking bar indicates the cathode.

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG4010CEGW	SOD123	Plastic surface-mounted package; 2 leads	SOD123

7. Marking

Table 4. Marking codes

Type number	Marking code
PMEG4010CEGW	G6

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	$T_j = 25\text{ }^{\circ}\text{C}$		-	40	V
I_F	forward current	$T_{sp} \leq 55\text{ }^{\circ}\text{C}$		-	1	A
$I_{F(AV)}$	average forward current	$\delta = 0.5$; $f = 20\text{ kHz}$; $T_{amb} \leq 70\text{ }^{\circ}\text{C}$; square wave	[1]	-	1	A
		$\delta = 0.5$; $f = 20\text{ kHz}$; $T_{sp} \leq 135\text{ }^{\circ}\text{C}$		-	1	A
I_{FRM}	repetitive peak forward current	$t_p \leq 1\text{ ms}$; $\delta \leq 0.25$		-	7	A
I_{FSM}	non-repetitive peak forward current	$t_p = 8\text{ ms}$; $T_{j(init)} = 25\text{ }^{\circ}\text{C}$; square wave		-	9	A
P_{tot}	total power dissipation	$T_{amb} \leq 25\text{ }^{\circ}\text{C}$	[2]	-	410	mW
			[1]	-	675	mW
T_j	junction temperature			-	150	$^{\circ}\text{C}$
T_{amb}	ambient temperature			-55	150	$^{\circ}\text{C}$
T_{stg}	storage temperature			-65	150	$^{\circ}\text{C}$

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1] [2]	-	-	305	K/W
			[1] [3]	-	-	185	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[4]	-	-	21	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2 .

[4] Soldering point of cathode tab.

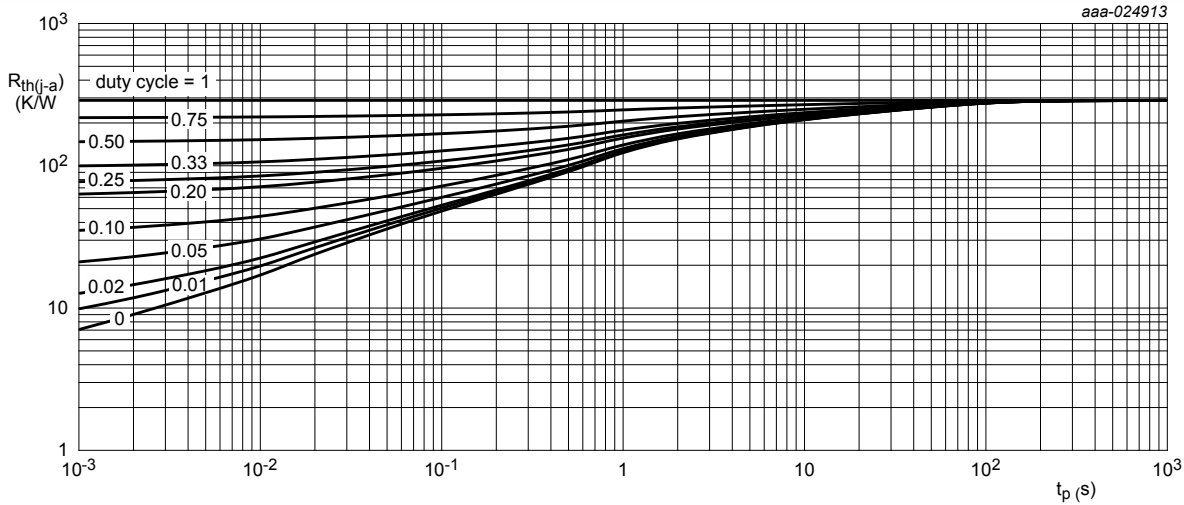


Fig. 1. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

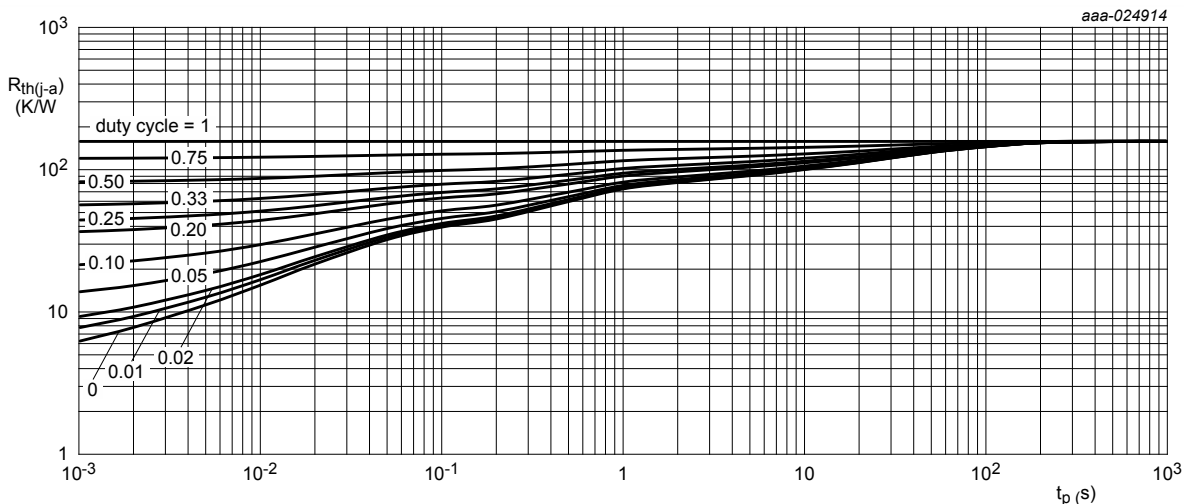


Fig. 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

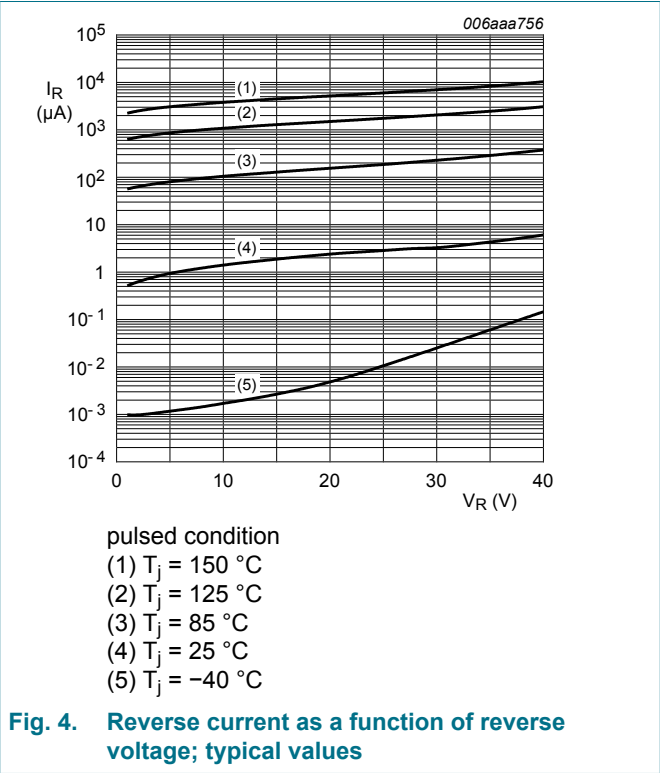
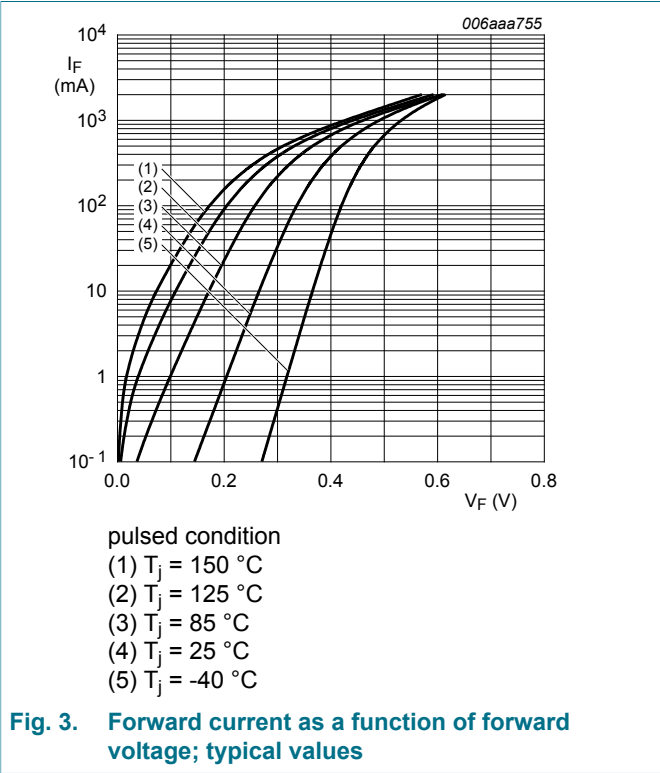
10. Characteristics

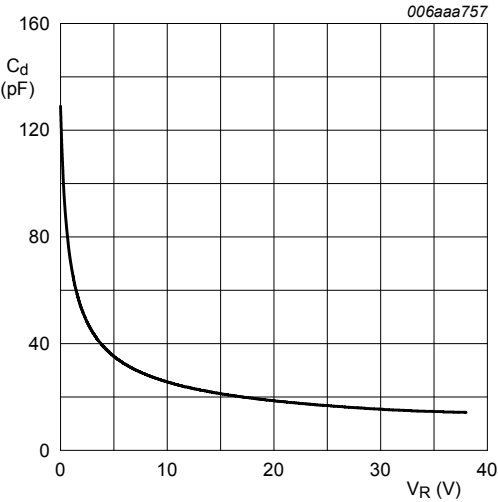
Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{(BR)R}$	reverse breakdown voltage	$I_R = 1\text{ mA}$; $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$; $T_j = 25\text{ }^\circ\text{C}$	40	-	-	V
V_F	forward voltage	$I_F = 1\text{ mA}$; $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$; $T_j = 25\text{ }^\circ\text{C}$	-	210	240	mV
		$I_F = 10\text{ mA}$; $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$; $T_j = 25\text{ }^\circ\text{C}$	-	270	310	mV
		$I_F = 100\text{ mA}$; $t_p \leq 300\text{ }\mu\text{s}$; $\delta \leq 0.02$; $T_j = 25\text{ }^\circ\text{C}$	-	340	390	mV

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		$I_F = 500\text{ mA}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02\text{ };$ $T_J = 25\text{ }^\circ\text{C}$		-	420	490	mV
		$I_F = 700\text{ mA}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02\text{ };$ $T_J = 25\text{ }^\circ\text{C}$		-	450	520	mV
		$I_F = 1\text{ A}; t_p \leq 300\text{ }\mu\text{s}; \delta \leq 0.02\text{ };$ $T_J = 25\text{ }^\circ\text{C}$		-	490	570	mV
I_R	reverse current	$V_R = 5\text{ V}; \text{pulsed}; T_J = 25\text{ }^\circ\text{C}$	[1]	-	0.8	-	μA
		$V_R = 10\text{ V}; \text{pulsed}; T_J = 25\text{ }^\circ\text{C}$	[1]	-	1.1	-	μA
		$V_R = 40\text{ V}; \text{pulsed}; T_J = 25\text{ }^\circ\text{C}$	[1]	-	6	50	μA
C_d	diode capacitance	$V_R = 1\text{ V}; f = 1\text{ MHz}; T_J = 25\text{ }^\circ\text{C}$		-	69	77	pF

[1] Very short test pulse to prevent junction self-heating.





f = 1 MHz; T_{amb} = 25 °C

Fig. 5. Diode capacitance as a function of reverse voltage; typical values

11. Test information

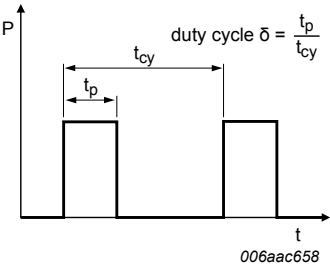


Fig. 6. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations:
 $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

12. Package outline

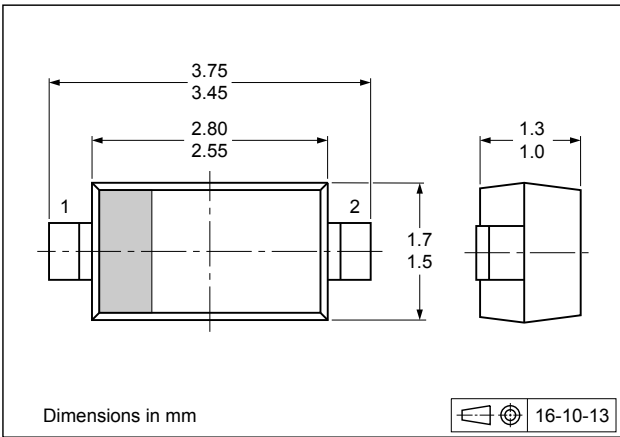


Fig. 7. Package outline SOD123

13. Soldering

SOD123

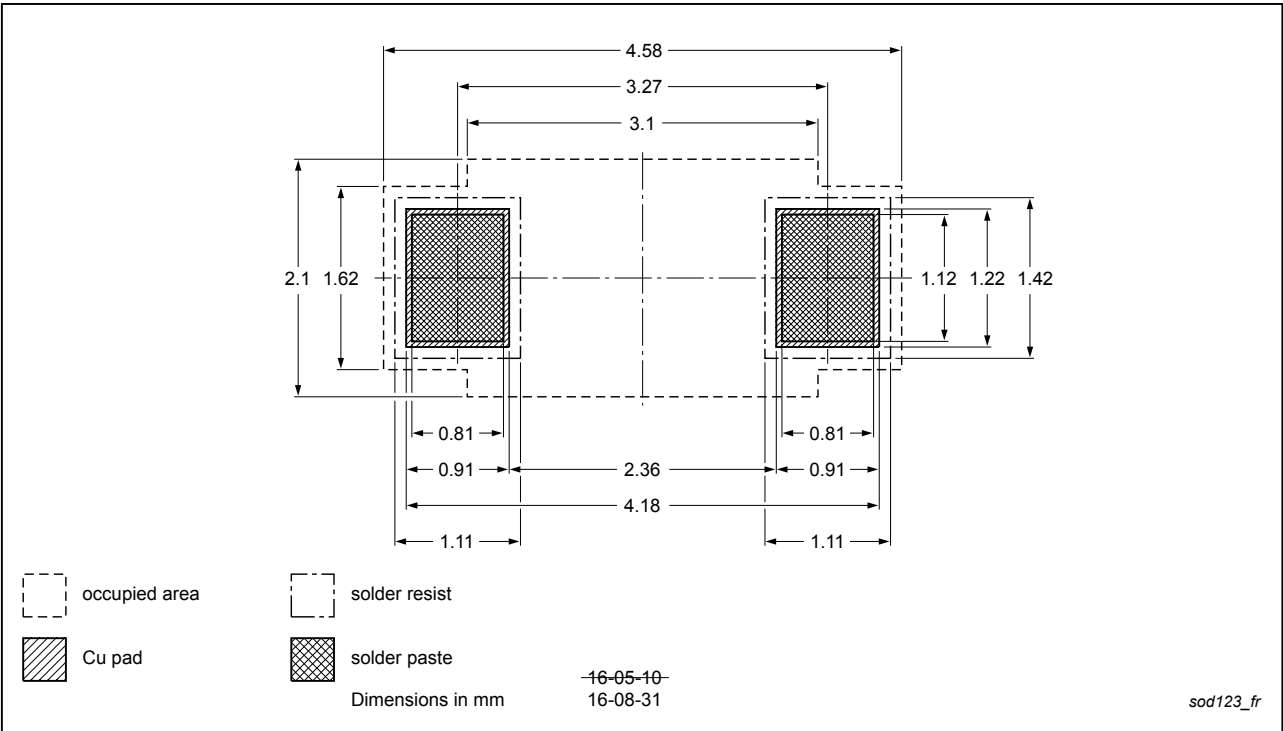


Fig. 8. Reflow soldering footprint for SOD123

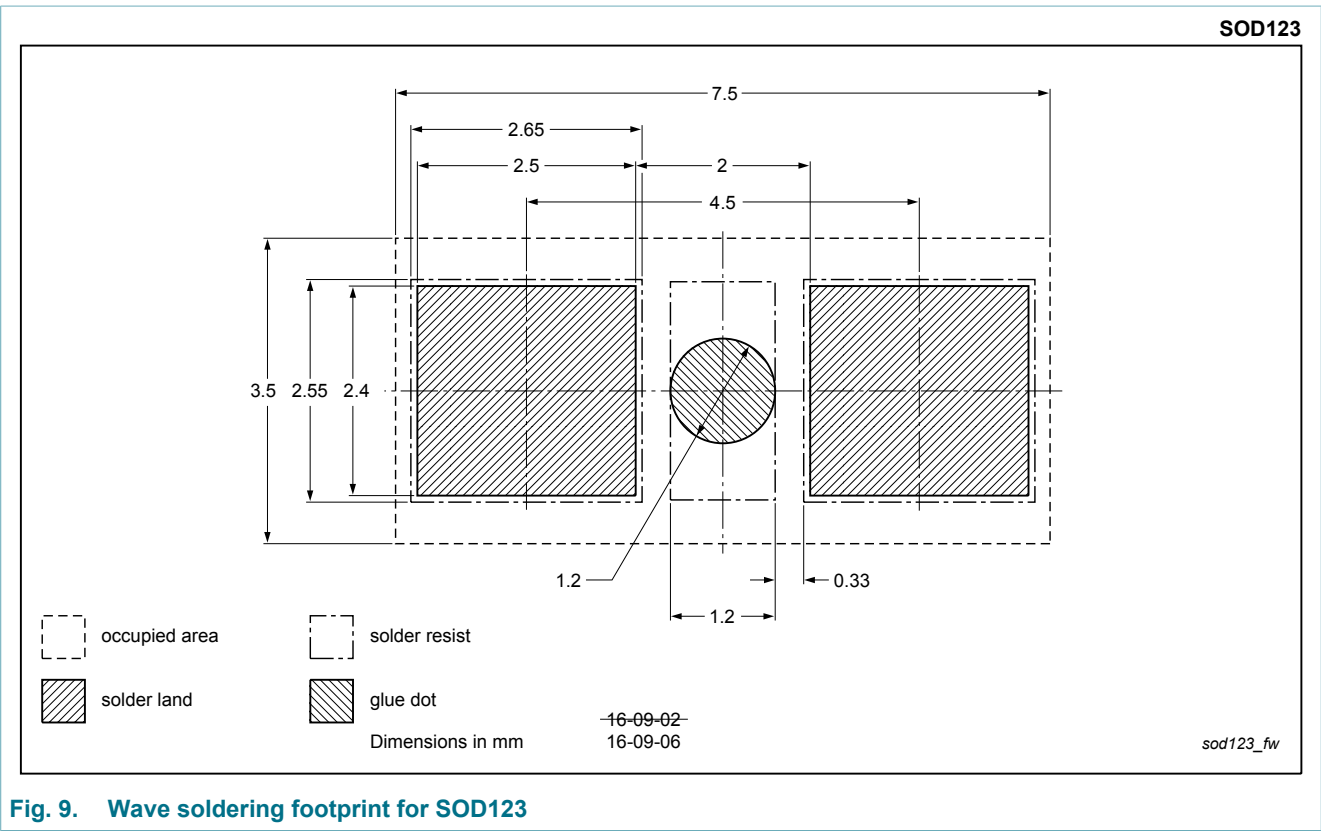


Fig. 9. Wave soldering footprint for SOD123

14. Revision history

Table 8. Revision history

Data sheet ID	Release date	Data sheet status	Change notice	Supersedes
PMEG4010CEGW v.1	20161123	Product data sheet	-	-

15. Legal information

Data sheet status

Document status ^{[1] [2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

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